# CyberOptics Features Industry-Best Airborne Particle Sensors and MRS Sensors at SEMICON Korea

Minneapolis, MN— January, 2018 — CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, announces that it will exhibit at SEMICON KOREA, scheduled to take January 23 - 25th, 2019 at the COEX in Seoul. The company will demonstrate its next-generation Airborne Particle Sensor™ technology (APS3) 300mm with new ParticleSpectrum™ software in Booth # A418.

CyberOptics' WaferSense® APS3 quickly monitors, identifies and enables troubleshooting of airborne particles in real time within semiconductor process equipment and automated material handling systems. The wireless device speeds equipment qualification, shortens equipment maintenance schedules and lowers equipment expenses. Now in a thinner and lighter form factor to travel through semiconductor tools with ease, the APS3 offers leading accuracy and sensitivity.
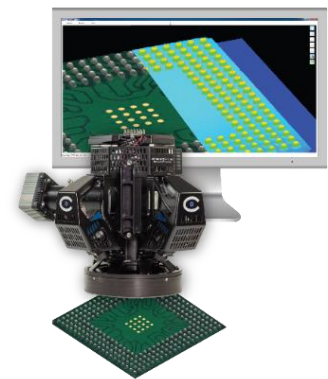
The APS3 solution includes ParticleSpectrum software – a touch-enabled interface with user-friendly functionality, making it simple to read, record and review small to large airborne particle data from multiple devices. Easily identify when and where the particles originate and see the effects of cleanings, adjustments and repairs in real-time.

Recognized as the world's most efficient and effective wireless airborne particle sensors and documented as the best-known method (BKM), APS devices have proven to deliver significant benefits. Semiconductor fabs have recognized up to 90% time savings, 95% expense reduction and up to 20X the throughput with half the labor relative to legacy surface scan wafer methods.
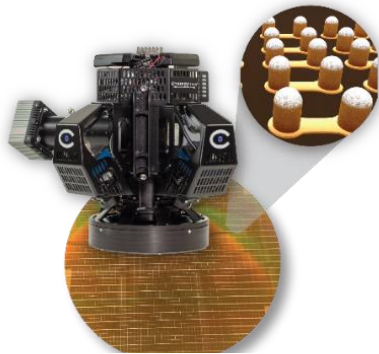
Wafer Bump Inspection

At SEMICON CyberOptics also will demonstrate the proprietary 3D Ultra High-Resolution Multi-Reflection Suppression (MRS) Sensor technology that meticulously identifies and rejects reflections caused by shiny components and surfaces. Effective suppression of multiple reflections is critical for highly accurate measurements. Offering an unmatched combination of accuracy and speed, MRS sensors are widely used for inspection and measurement in the SMT, metrology and semiconductor markets. This best in class, ultra high-resolution technology used in back-end inspection applications, is ideally suited for IC package, wafer bump inspection and mid-end semiconductor applications where the highest degree of precision is required.

IC Package Inspection

About the WaferSense®, ReticleSense® and PanelSense™ Line

The WaferSense and ReticleSense measurement portfolio including the Auto Leveling System (ALS & ALSR), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensors (APS 2, 3, APSR & APSRQ) and the new Auto Multi Sensor (AMS & AMSR), are available in various wafer shaped and reticle shaped form factors depending on the device. The PanelSense measurement portfolio including the Airborne Particle Sensor (APS-FPD) is available in a flat panel display compatible form factor.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics' sensors are used in SMT, semiconductor and metrology markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; the timing of orders and shipments of our products, particularly our 3D MRS-enabled AOI systems; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 3D CMM system, products for semiconductor mid-end and advanced packaging inspection applications and CyberGage360 product; costly and time consuming litigation with third parties related to intellectual property infringement; and other factors set forth in the company's filings with the Securities and Exchange Commission.

# # #

For additional information, contact:

Carla Furanna, CyberOptics, 952-820-5837, cfuranna@cyberoptics.com